



## **General Description**

The AOZ8937DI is a 7-channel combo transient voltage suppressor array designed to protect high-speed data lines such as USB3.1, Thunderbolt, Displayport, and VBUS from damaging ESD events.

This device incorporates 6 channels for high speed data lines and 1 channel for VBUS.

The AOZ8937DI comes in a RoHS compliant and Halogen Free DFN4.1x2.0 package and is rated for -40°C to +125°C junction temperature range.

## Features

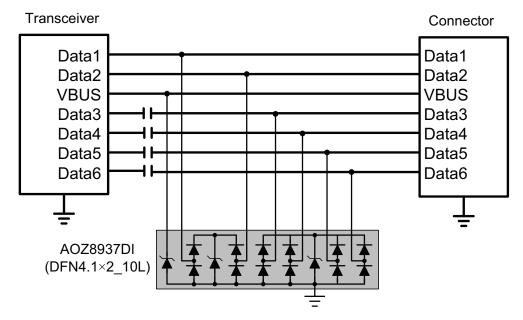
- IEC61000-4-2, ESD immunity (Contact/Air)
  - ± 12/15 kV (High Speed Data lines)
  - ± 30/30 kV (VBUS)
- IEC61000-4-5, Surge Immunity (8/20μs)
  - $-\pm$  3 A (High Speed Data lines)  $-\pm$  5 A (VBUS).
- Capacitance between I/O to GND
  - 0.3 pF (High Speed Data lines)
  - 16 pF (VBUS)

### Applications

- USB3.1/3.2&USB2.0
- Thunderbolt
- Displayport
- Notebook computers



## **Typical Application**





## **Ordering Information**

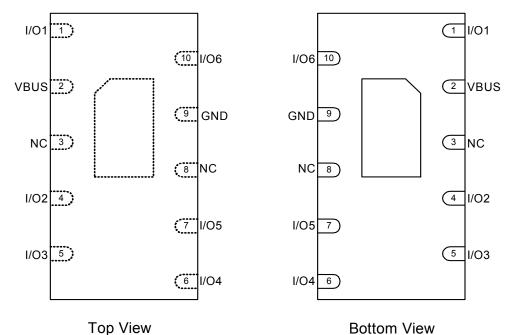
Part Number	Ambient Temperature Range	Package	Environmental
AOZ8937DI	-40°C to +125°C	DFN4.1X2_10L	Green Product



AOS Green Products use reduced levels of Halogens, and are also RoHS compliant.

Please visit www.aosmd.com/media/AOSGreenPolicy.pdf for additional information.

# **Pin Configuration**



## Absolute Maximum Ratings

Exceeding the Absolute Maximum ratings may damage the device.

Parameter	Ratir	ng
	I/O1 to I/O6 (Pin 1, 4, 5, 6, 7,10)	VBUS (Pin2)
Storage Temperature (T <sub>S</sub> )	-65°C to +150°C	-65 °C to +150°C
ESD Rating per IEC61000-4-2, contact <sup>(1)</sup>	±12kV	±30kV
ESD Rating per IEC61000-4-2, air <sup>(1)</sup>	±15kV	±30kV
8/20µs Surge IEC61000-4-5	±3 A	±5 A

Notes:

1. IEC 61000-4-2 discharge with C\_Discharge = 150pF, R\_Discharge = 330  $\Omega$ .

2. Human Body Discharge per MIL-STD-883, Method 3015 C<sub>Discharge</sub> = 100pF, R<sub>Discharge</sub> =  $1.5k\Omega$ .

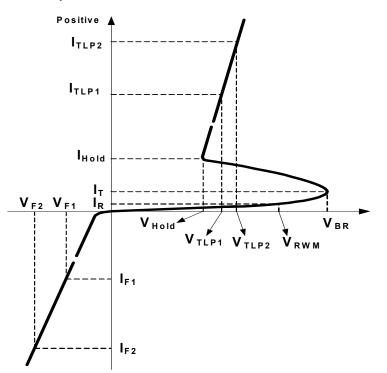
## **Maximum Operating Ratings**

Parameter	Rating
Junction Temperature (T <sub>J</sub> )	-40°C to +125°C



## **Electrical Characteristics**

 $T_A$  = 25°C unless otherwise specified. Any I/O Pin to GND.



		I/O1 to I/O6 (Pin 1, 4, 5, 6, 7, 10)						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units		
V <sub>RWM</sub>	Reverse Working Voltage				5.5	V		
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>T</sub> = 100μA	6.5			V		
I <sub>R</sub>	Reverse Leakage Current	V <sub>T</sub> = Max. V <sub>RWM</sub>			100	μA		
V <sub>F</sub>	Forward Voltage		0.7	0.85	0.95	V		
V <sub>CL</sub>	Clamping Voltage <sup>(3)(4)</sup> (100ns Transmission Line Pulse)	I <sub>TLP</sub> = 1A I <sub>TLP</sub> = -1A I <sub>TLP</sub> = 16A		3 -1 12	4 -2 15	v		
		I <sub>TLP</sub> = -16A		-8	-10			
R <sub>DYN</sub>	Dynamic Resistance <sup>(3)(4)</sup>	I <sub>TLP</sub> = 8A to 16A I <sub>TLP</sub> = -8A to -16A		0.35 0.40		Ω		
I <sub>PP</sub>	Peak Pulse Current <sup>(3)</sup> IEC61000-4-5 Surge 8/20µs				±3	A		
V	Clamping Voltage <sup>(3)</sup>	$I_{PP} = 1A$ $I_{PP} = -1A$		2 -1.8		V		
V <sub>CL</sub>	IEC61000-4-5 Surge 8/20µs	I <sub>PP</sub> = 3A I <sub>PP</sub> = -3A		3.7 -3		V		
Cj	Junction Capacitance	V <sub>I/O</sub> = 0V, f = 1MHz		0.3	0.45	pF		

### Notes:

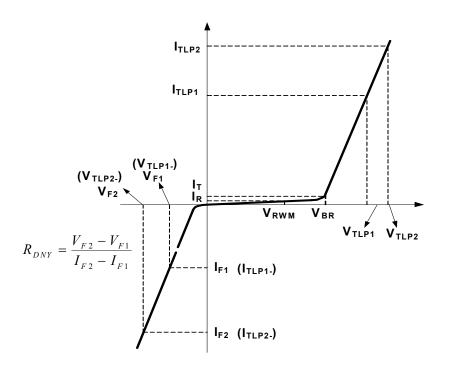
3. These specifications are guaranteed by design and characterization.

4. Measurements performed using a 100ns Transmission Line Pulse (TLP) system.



### **Electrical Characteristics**

 $T_A$  = 25°C unless otherwise specified. Any I/O Pin to GND.



	VBUS (Pin 2)										
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units					
V <sub>RWM</sub>	Reverse Working Voltage				5.5	V					
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>T</sub> = 1mA	6			V					
I <sub>R</sub>	Reverse Leakage Current	V <sub>T</sub> = Max, V <sub>RWM</sub>			1	μA					
V <sub>F</sub>	Forward Voltage		0.65	0.85	0.95	V					
V	Clamping Voltage <sup>(3)(4)</sup>	I <sub>TLP</sub> = 1A I <sub>TLP</sub> = -1A		8 -1	10 -2	v					
V <sub>CL</sub>	(100ns Transmission Line Pulse)	I <sub>TLP</sub> = 16A I <sub>TLP</sub> = -16A		10 -10	12 -15	v					
I <sub>PP</sub>	Peak Pulse Current <sup>(3)</sup> IEC61000-4-5 Surge 8/20μs				±5	А					

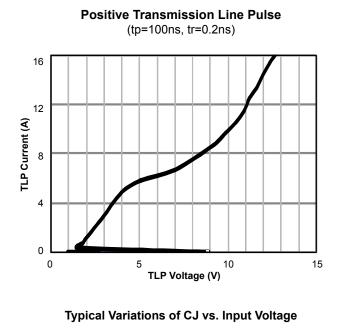
### Notes:

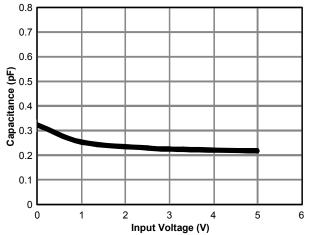
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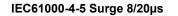


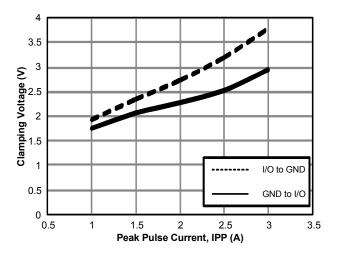
# Typical Performance Characteristics (I/O1 to I/O6)





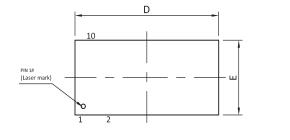
Negative Transmission Line Pulse (tp=100ns, tr=0.2ns)

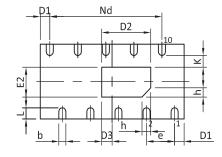






# Package Dimensions, DFN4.1x2.0-10L, EP1\_S

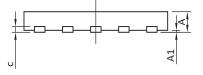




TOP VIEW

SIDE VIEW

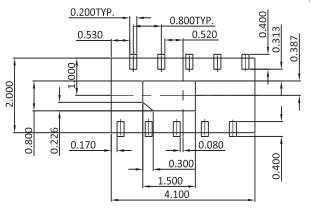
BOTTOM VIEW



SIDE VIEW

	DIMENS	ION IN MI	LLIMETRES	DIM	ENSION IN I	NCHS	
SYMBOLS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	0.45	0.50	0.55	0.018	0.020	0.022	
A1		0.02	0.05		0.001	0.002	
b	0.15	0.20 0.15 4.10 0.25	0.20	0.25	0.006	0.008	0.010
С	0.10		0.20	0.004	0.006	0.008	
D	4.00			4.20	0.157	0.161	0.165
D1	0.20			0.30	0.008	0.010	0.012
D2	1.30	1.40	1.50	0.051	0.055	0.059	
D3	0.25	0.30	0.35	0.010	0.012	0.014	
е		0.80 BSC	0.80 BSC 0.031 BSC				
Nd		3.20 BSC		0.126 BSC			
E	1.90	2.00	2.10	0.075	0.079	0.083	
E2	0.70	0.80	0.90	0.028	0.031	0.035	
K	0.20			0.008			
L,	0.25	0.30	0.35	0.010	0.012	0.014	
h	0.15	0.20	0.25	0.006	0.008	0.010	

## LAND PATTERN RECOMMENDATIONS



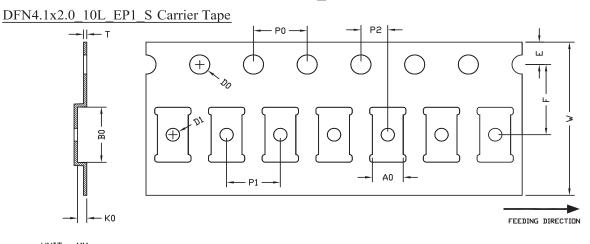
UNIT: mm

NOTES

1. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

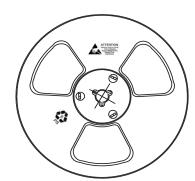


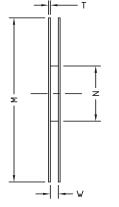
# Tape and Reel Dimensions, DFN4.1x2.0-10L, EP1\_S

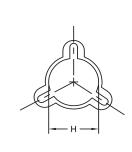


UNII: MM												
PACKAGE	A0	B0	К0	DO	D1	v	E	F	P0	P1	P2	т
DFN4.1×2.0	2.30 ±0.05	4.30 ±0.05	0.70 ±0.05	1.50 +0.1 -0.0	1.00 Min.	12.00 +0.30 -0.10	1.75 ±0.10	5.50 ±0.05	4.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.25 ±0.03

### DFN4.1x2.0\_10L\_EP1\_S\_Reel



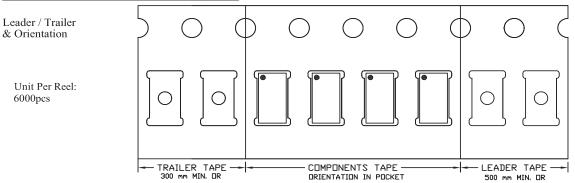




UNIT: MM

TAPE SIZE	REEL SIZE	м	Ν	¥	Т	н	к	S	G	R	V
12 mm	ø329	Ø329.00 ±1.00	ø100.00 ±1.00	12.80 ±1.00	2.00 ±0.30	ø13.30 ±0.30					

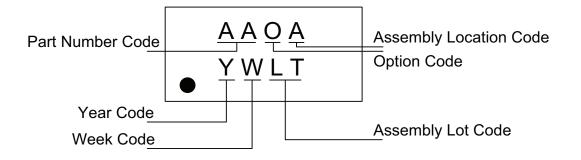
### DFN4.1x2.0\_10L\_EP1\_S Package Tape





## **Part Marking**

# AOZ8937DI (DFN4.1x2.0\_10L)



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